

ABSTRACT OF THE DISCLOSURE

Electrical lead-through systems from atmospheric into vacuum environments are presented. Electrical feed-through structures (EFTS) comprised of a multiplicity of parallel connection lines used to operate e-beam tip-array sources in high vac environments for chip lithography are disclosed. In one embodiment, an EFTS comprises a sheet of insulating material having conductive tracks extending along portions of the sheet and a vacuum seal separating one portion from another portion of the sheet so as to maintain a pressure differential among multiple portions of the sheet.